

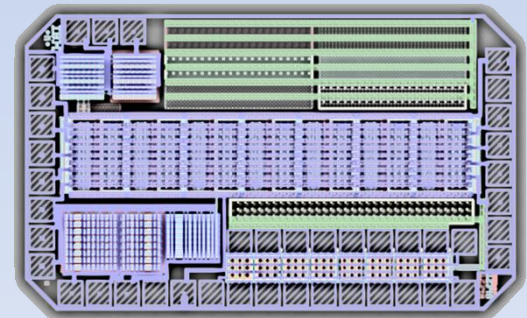
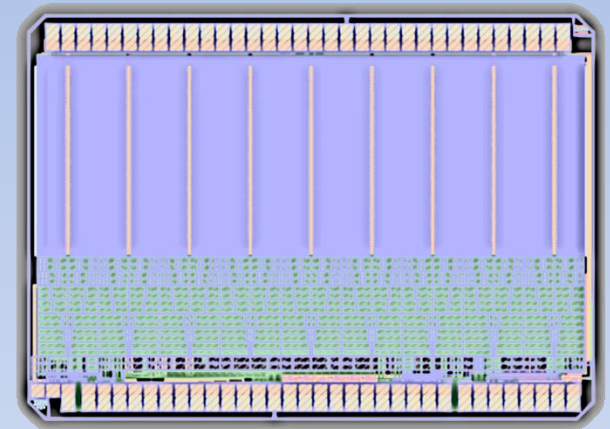
T3-based MAPS' in CMOS 130nm

CPIX14 – Bonn – September 14-16, 2014

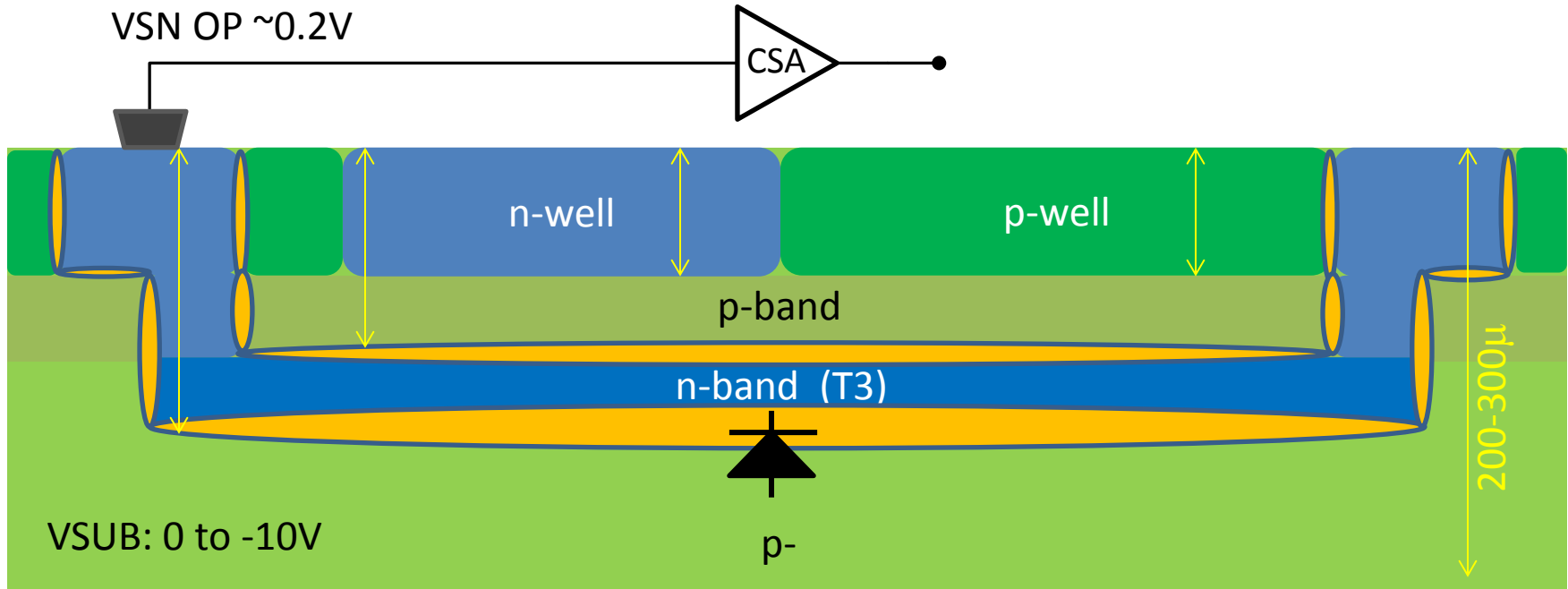
Abderrezak Makkaoui, Maurice Garcia-Sciveres, Dario Gnani,
Brad Axen, Sam Kohn, Jakob Sandberg, Laser Kaplan
September 16, 2014

Outline

- **General intro**
 - APS structure and design target
- **Test chip 1**
 - Description (diagrams+layout+sims)
 - Rad source & beam tests
 - Rad Tolerance
 - Analysis & Modeling
- **Test chip 2**
 - Description (layout)
 - IV & CV measurements
 - Current Status
- **Conclusions**
 - Open questions
 - Future plans

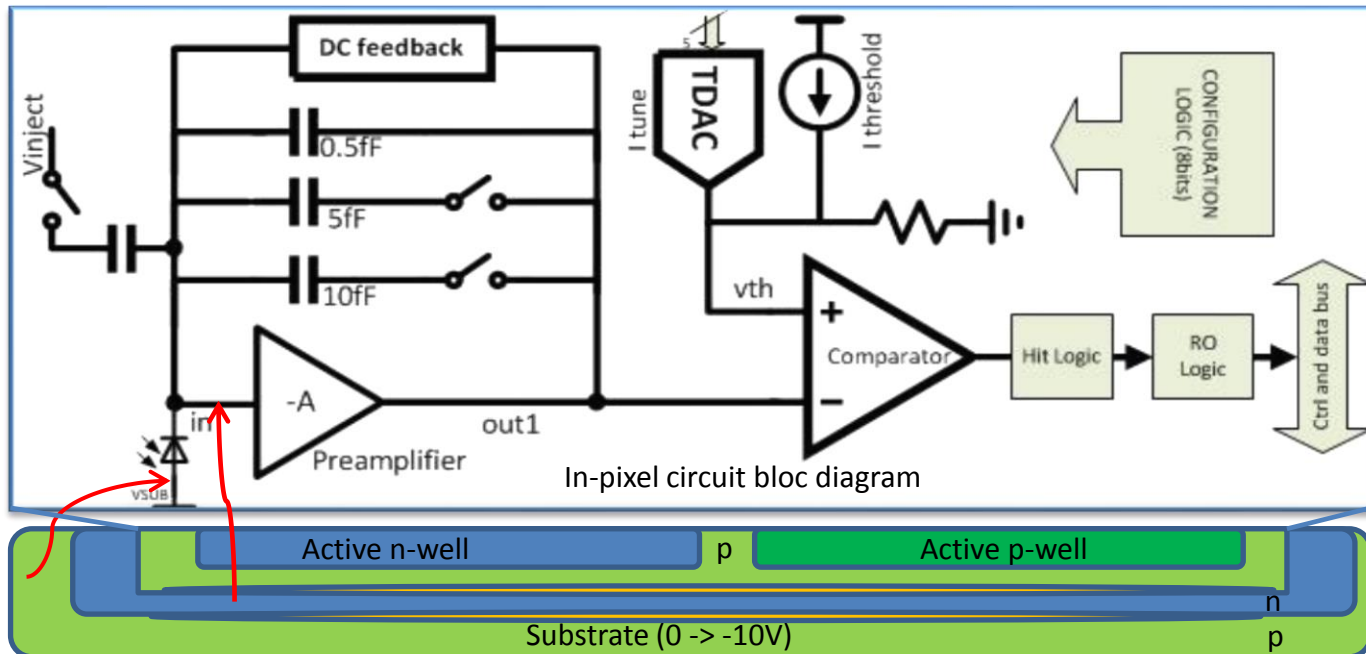


Introduction: Sensor Structure



- Using deep n-band (T3) electrode as sense node
- Doping and implant thickness not specified in process docs
 - Some info from models...
- Several junction of different nature contribute to sense node
 - Substrate doping higher than ideal...

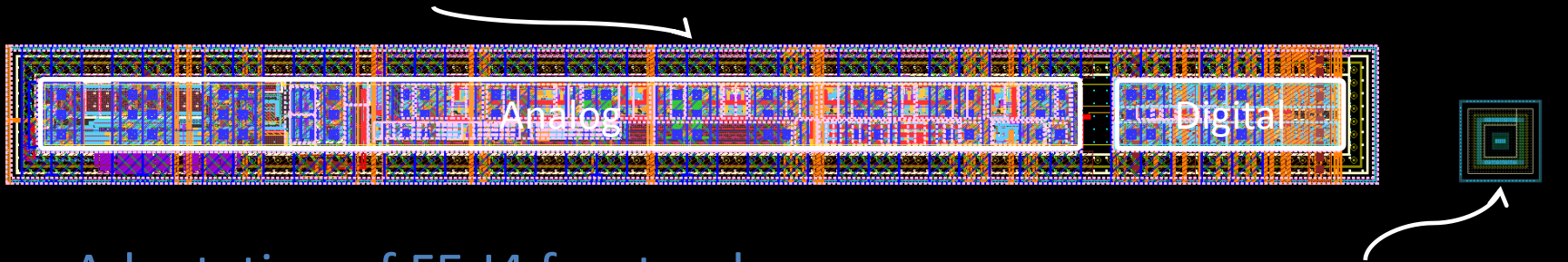
Design: Pixel Electronics



- Based on FE-I4 TOT design w/ additional gain configuration
- Minimalistic low-risk digital pixel for hit counting and digital cross-talk tests

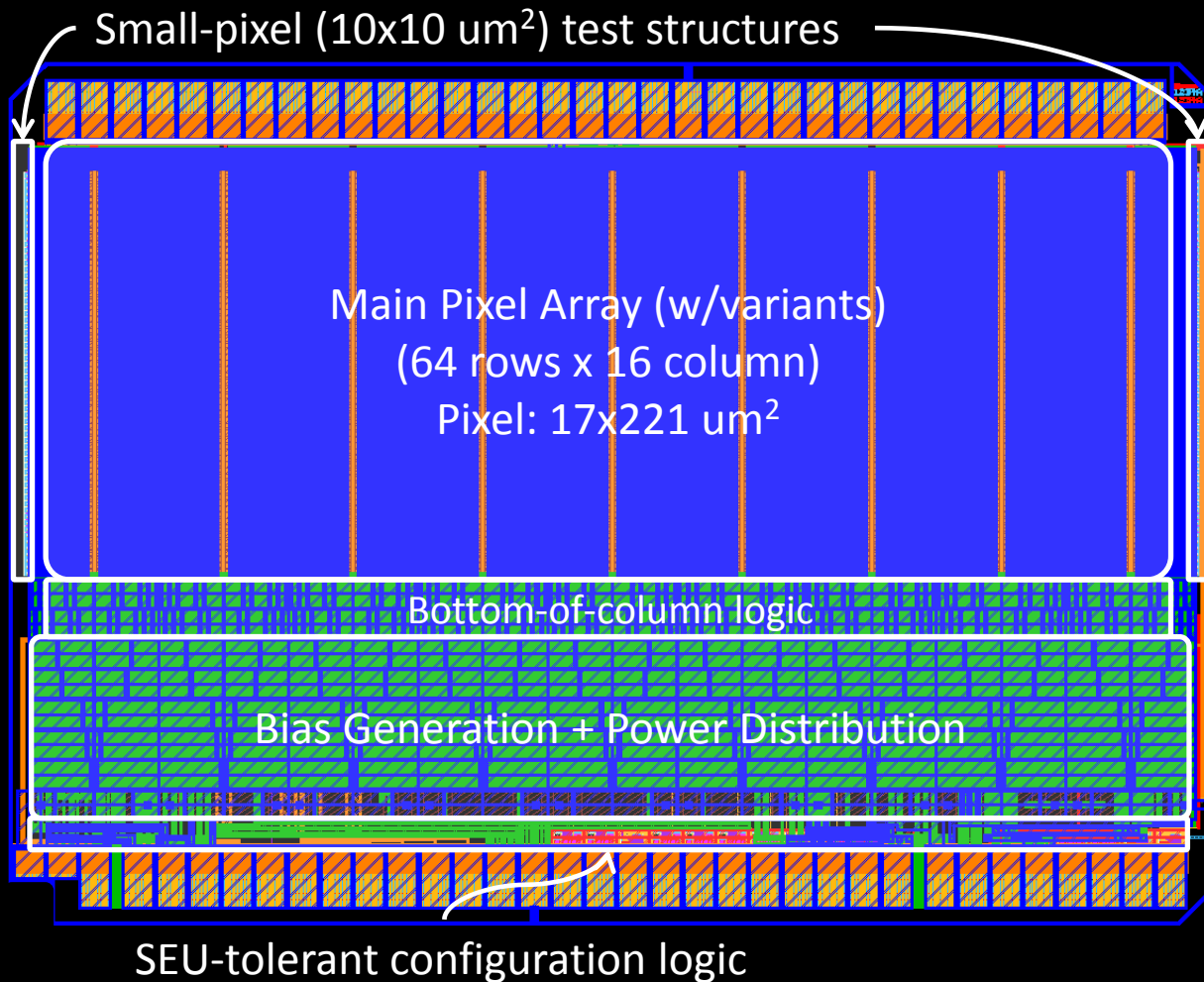
Design: Pixel Layout

Large-pixel ($17 \times 221 \text{ } \mu\text{m}^2$) - different 'flavors'



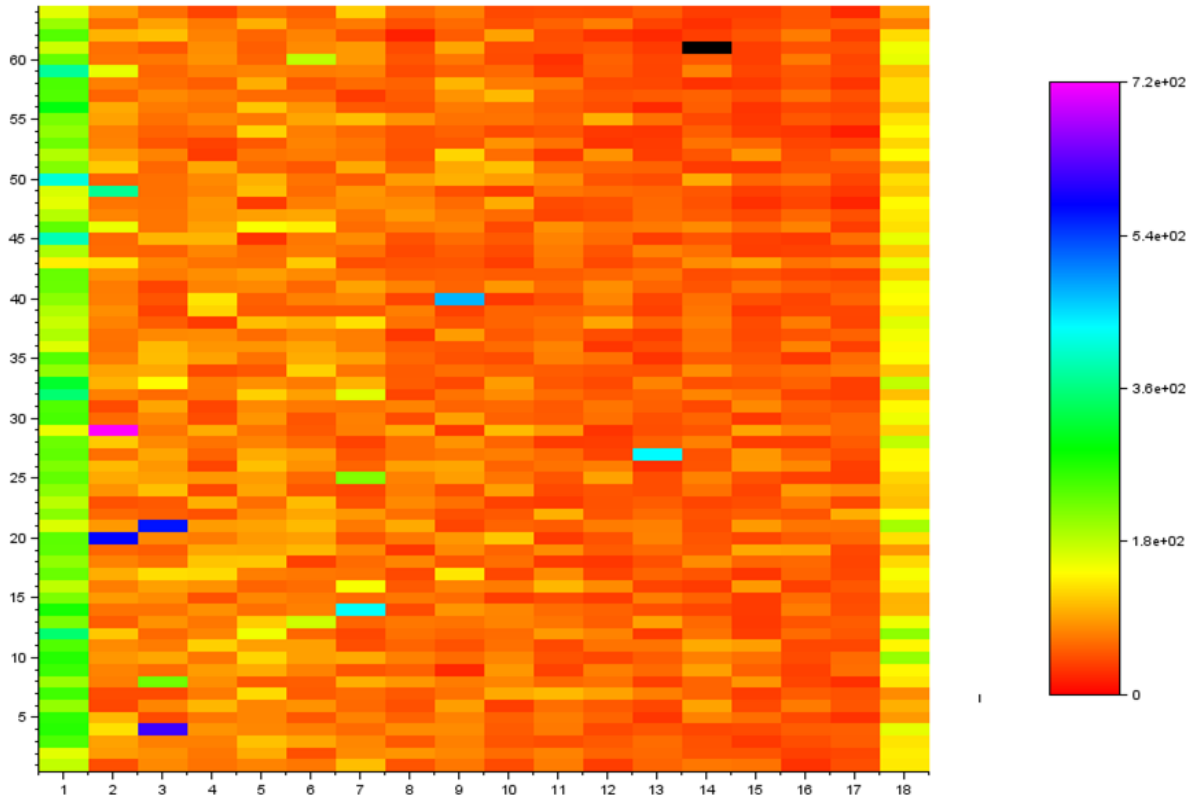
- Adaptation of FE-I4 frontend
- Minimal full-custom logic in pixel
 - Hit count
 - Digital crosstalk tests
- Sensor layout variants:
 - Optimized for crosstalk
 - Optimized for capacitance
 - No DRC violation
- Minimum size pixel
 - Minimal noise test
 - Spectroscopy

Design: T3MAPS_P1 Layout



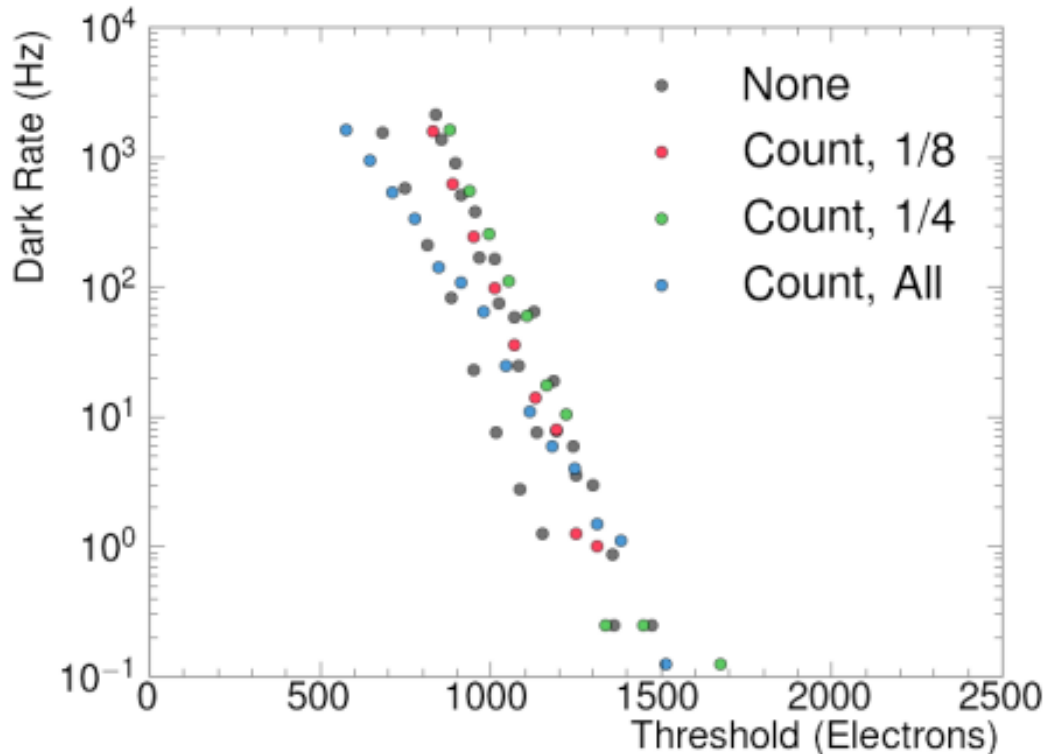
- Adapt existing FE, BOC and IO structures from FE-I4
- Minimal full-custom logic in pixel
- Test sensor:
 - Efficiency
 - Hybrid collection effects
 - Charge-sharing
 - Crosstalk
- Test electronics
 - Analog front-end
 - Layout variants

Experimental: Array Hit Map

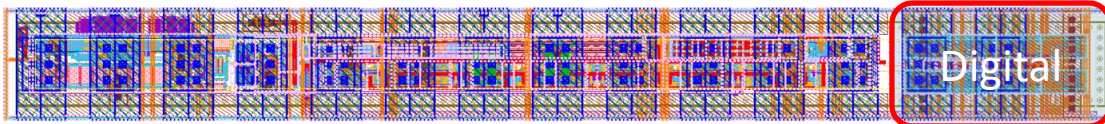


- Sealed source hit test:
- Reasonable yield
 - Reasonable threshold uniformity before tuning
 - Side columns instrument micro-pixels
 - Non-quantitative analysis for efficiency

Experimental: Digital Cross-talk

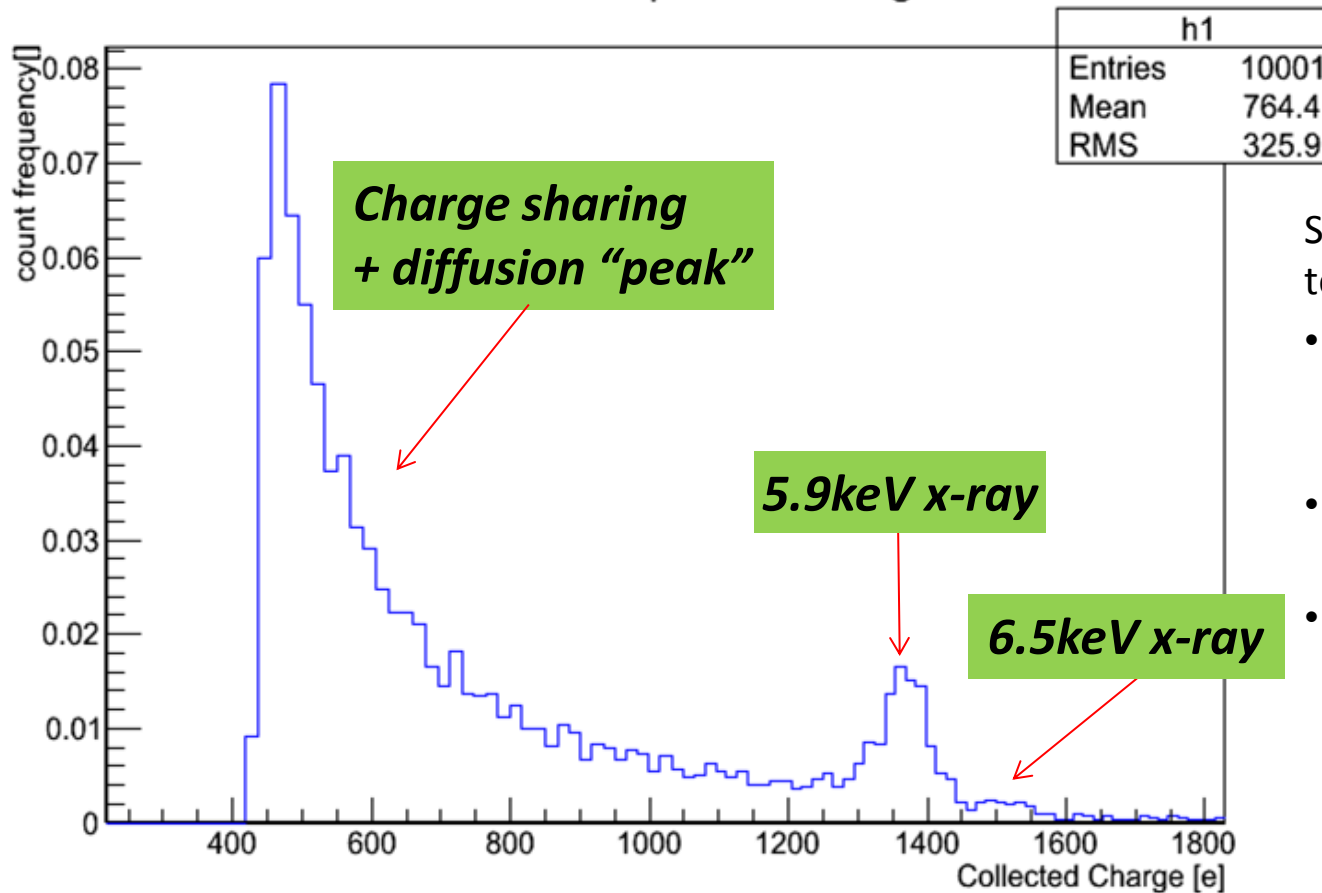


- Dark noise hit test:
- Negligible influence of digital activity
 - Possible mitigation technique possible but not needed



Experimental: small pixel spectra

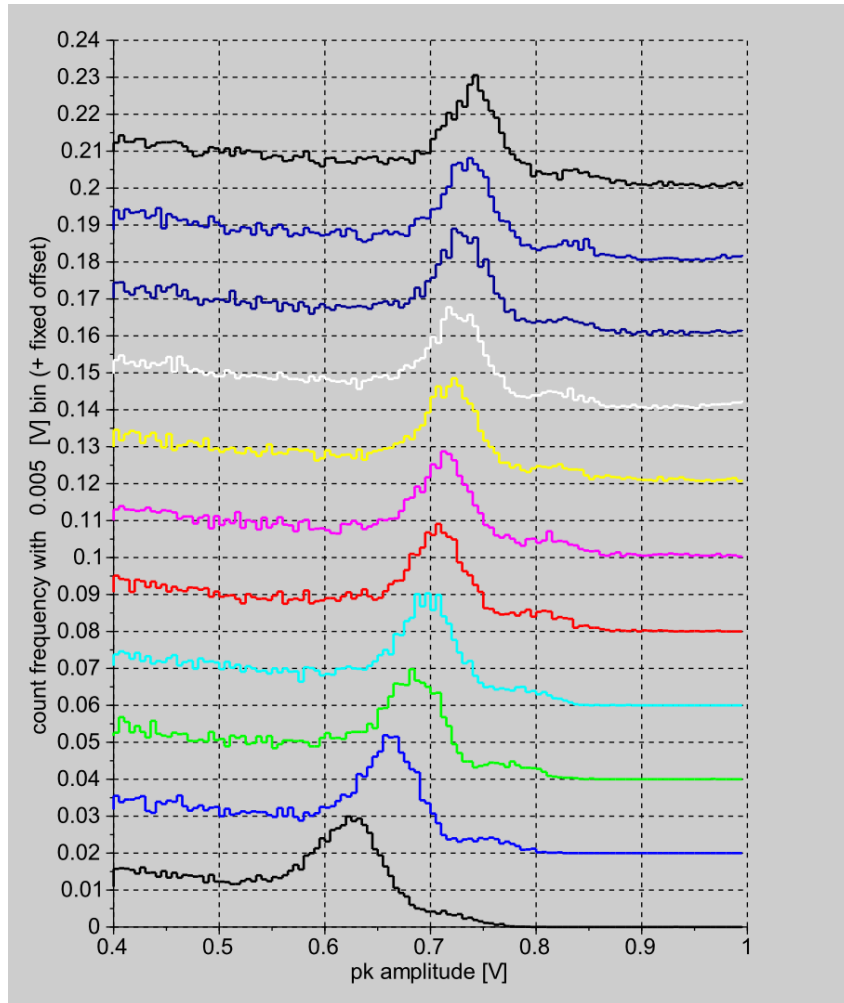
T3MAPS - Fe55 Spectrum - High Gain



Sealed source spectrum test:

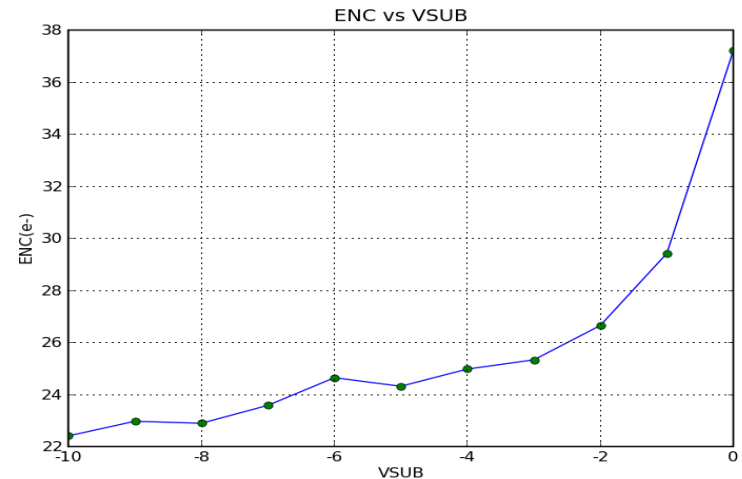
- Charge calibration based on injection cap (known to +/-20%)
- Output follower non-linearity for large signal
- Confirms
 - Dominant diffusion contribution
 - Critical role of threshold level

Experimental: Reverse Bias Effect

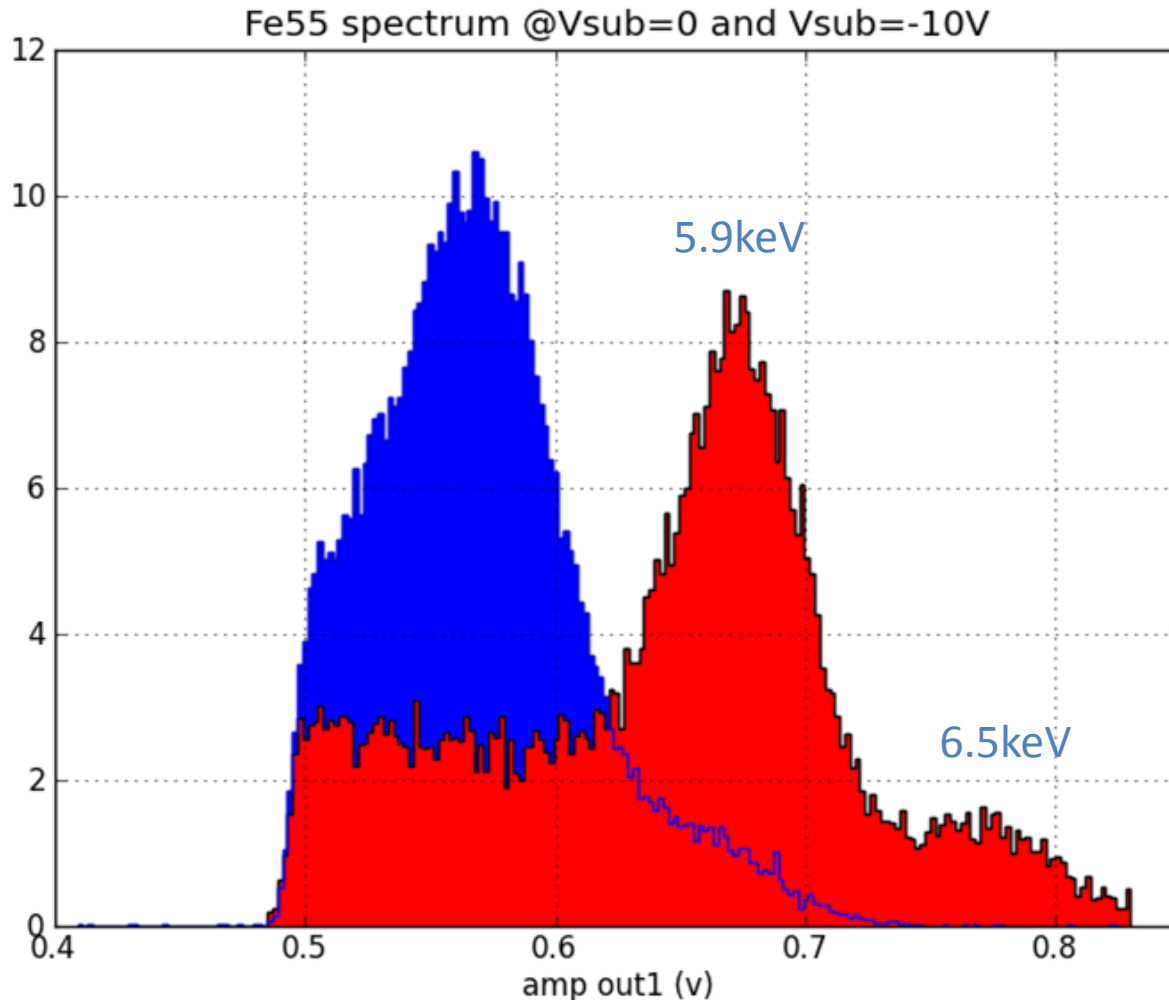


Sealed source hit test:

- Increase in gain and resolution as a function of reverse bias voltage
- Increase in 'large' hits above max expected energy
 - pile-up OR
 - avalanche effects (?)



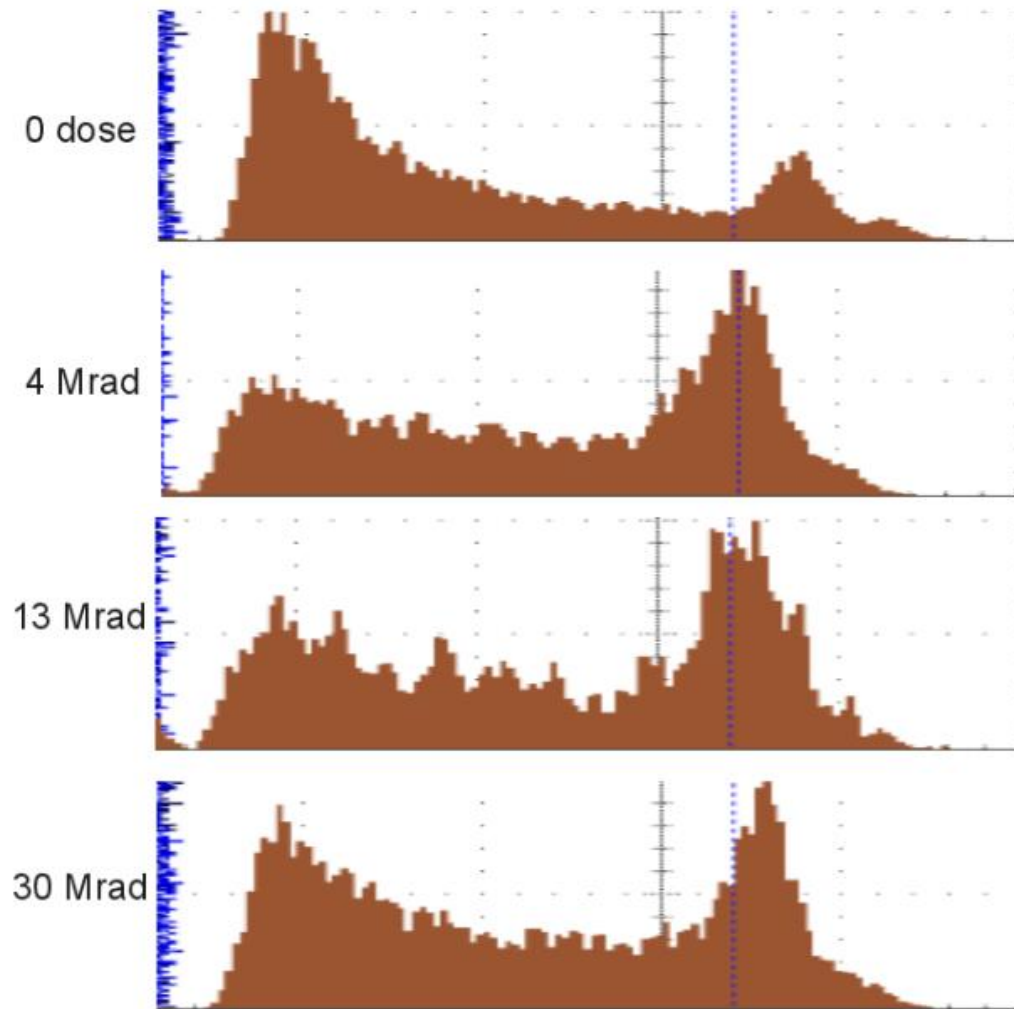
Experimental: small pixel spectra



Sealed source
spectrum test:

- Small pixel low noise level allows for resolving Fe55 double peak
- Confirms
 - charge calibration
 - noise level
 - substrate bias effect

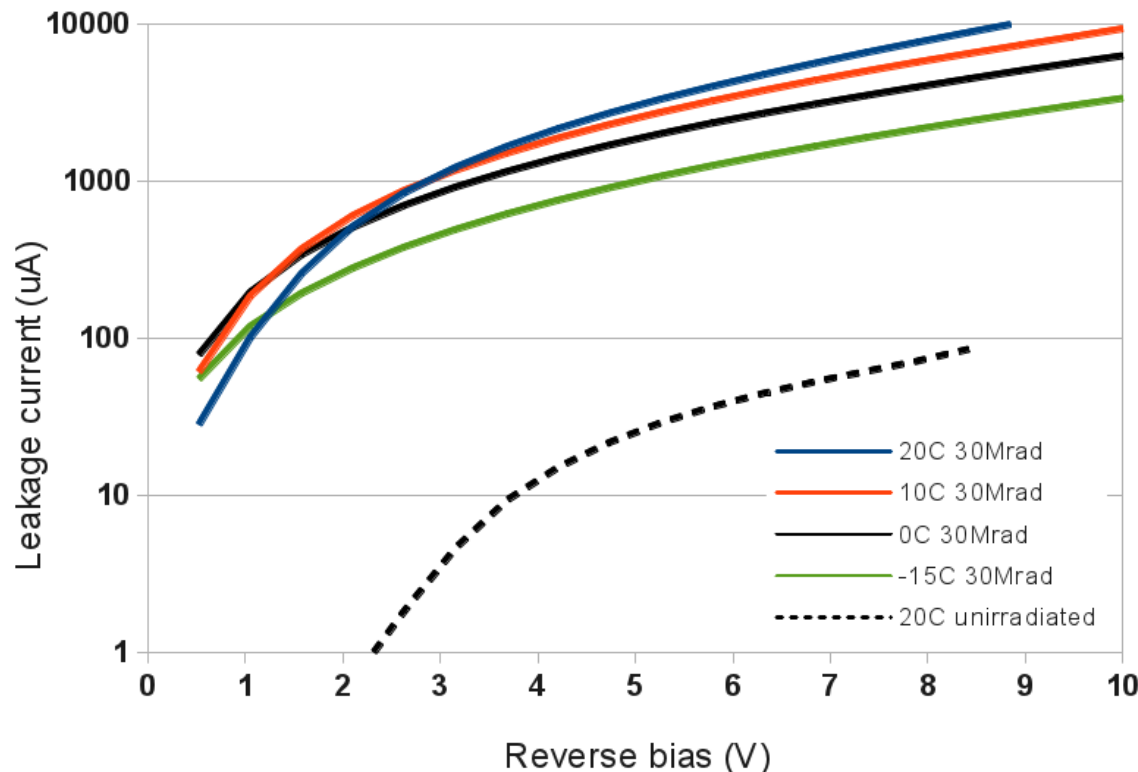
Experimental: total dose effects



Fe55 detection after 800 MeV proton irradiation:

- Significant variation in the ratio of drift-to-diffusion signal
 - Trap-induced reduction in diffusion length (?)
- Slight increase in noise
 - Harder to resolve Fe55 double peak
 - Based on similar exposure times...

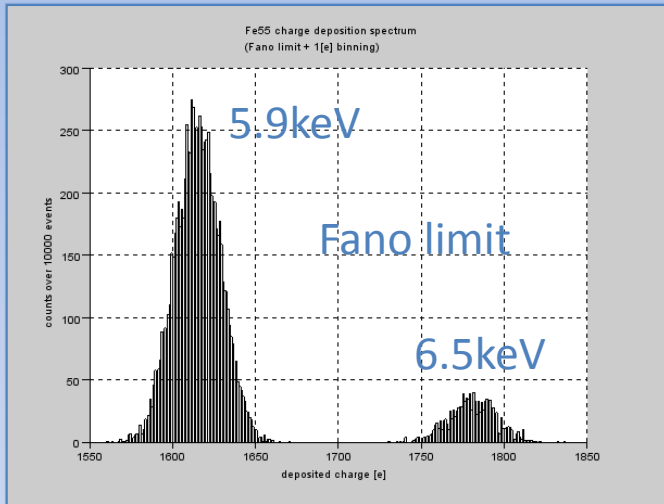
Experimental: total dose effects



Biasing after gamma irradiation:

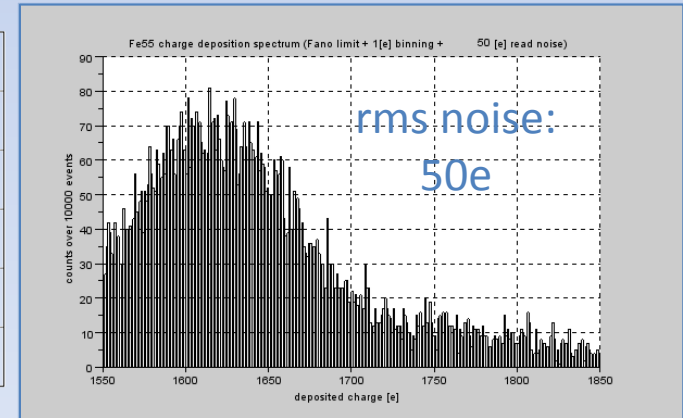
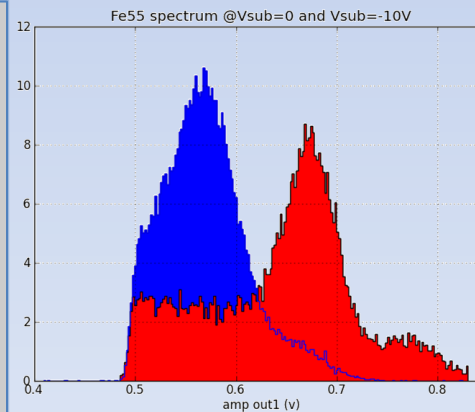
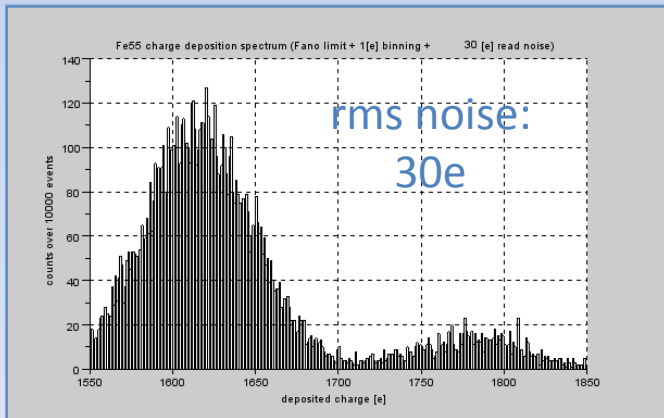
- 2 orders of magnitude increase in leakage current
- Limited improvements at lower temperatures

SIM: Drift Contribution

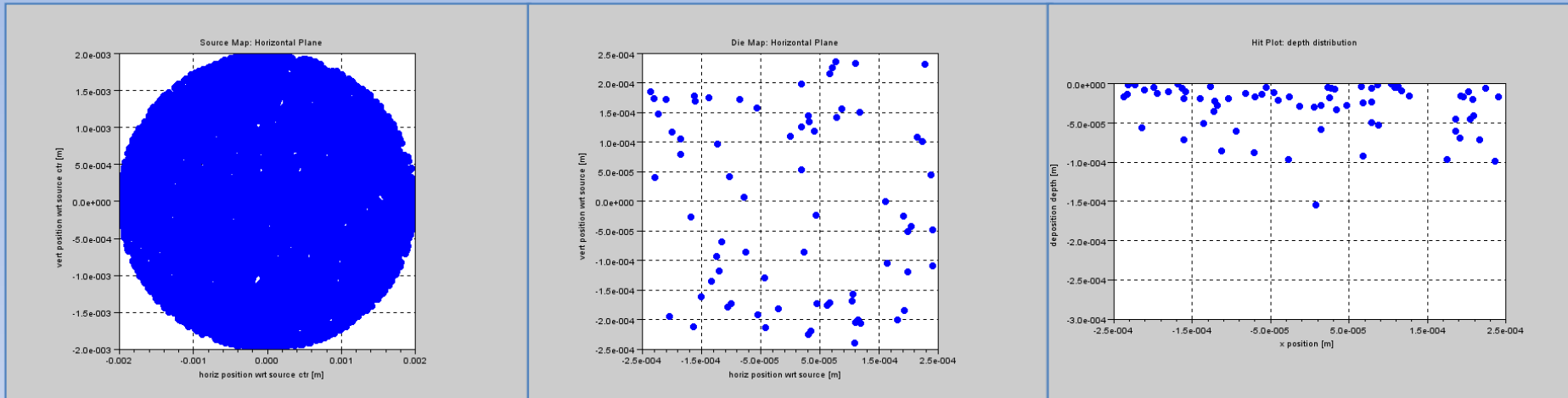


Montecarlo sim of drift signal from Fe55 source as a function of readout noise (for a fixed number of hits):

- Confirms input-referred noise magnitude ($\sim 30e$)
- Confirms correct interpretation of spectrum peaks



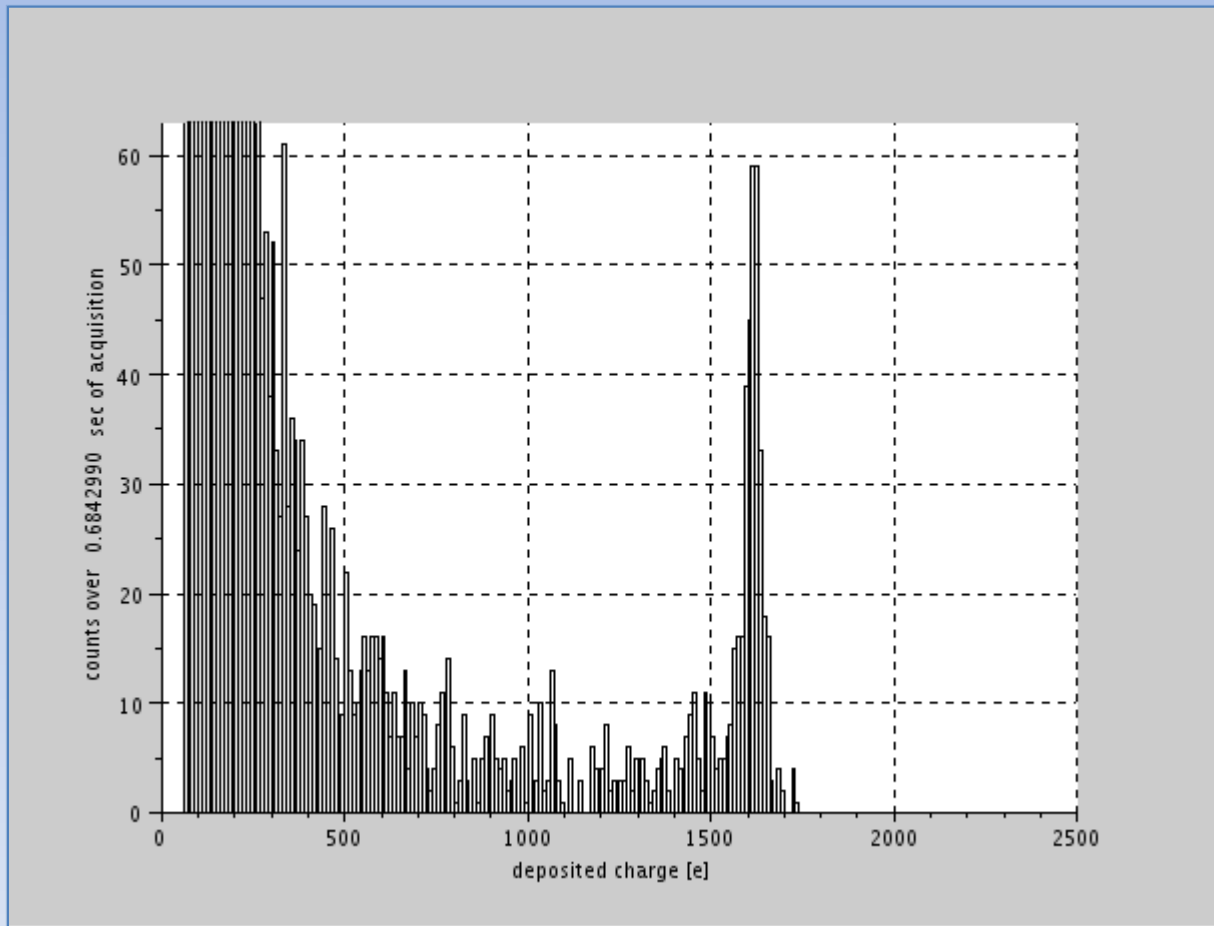
SIM: Diffusion-Drift Spectrum



Montecarlo sim of diffusion signal from sealed Fe55 source:

- Only 5.9keV photons propagated
- Photon statistics
- Source activity and geometry
- Interposed materials
- Stat. charge deposition from photons in Si
- Stat. of charge diffusion-recombination

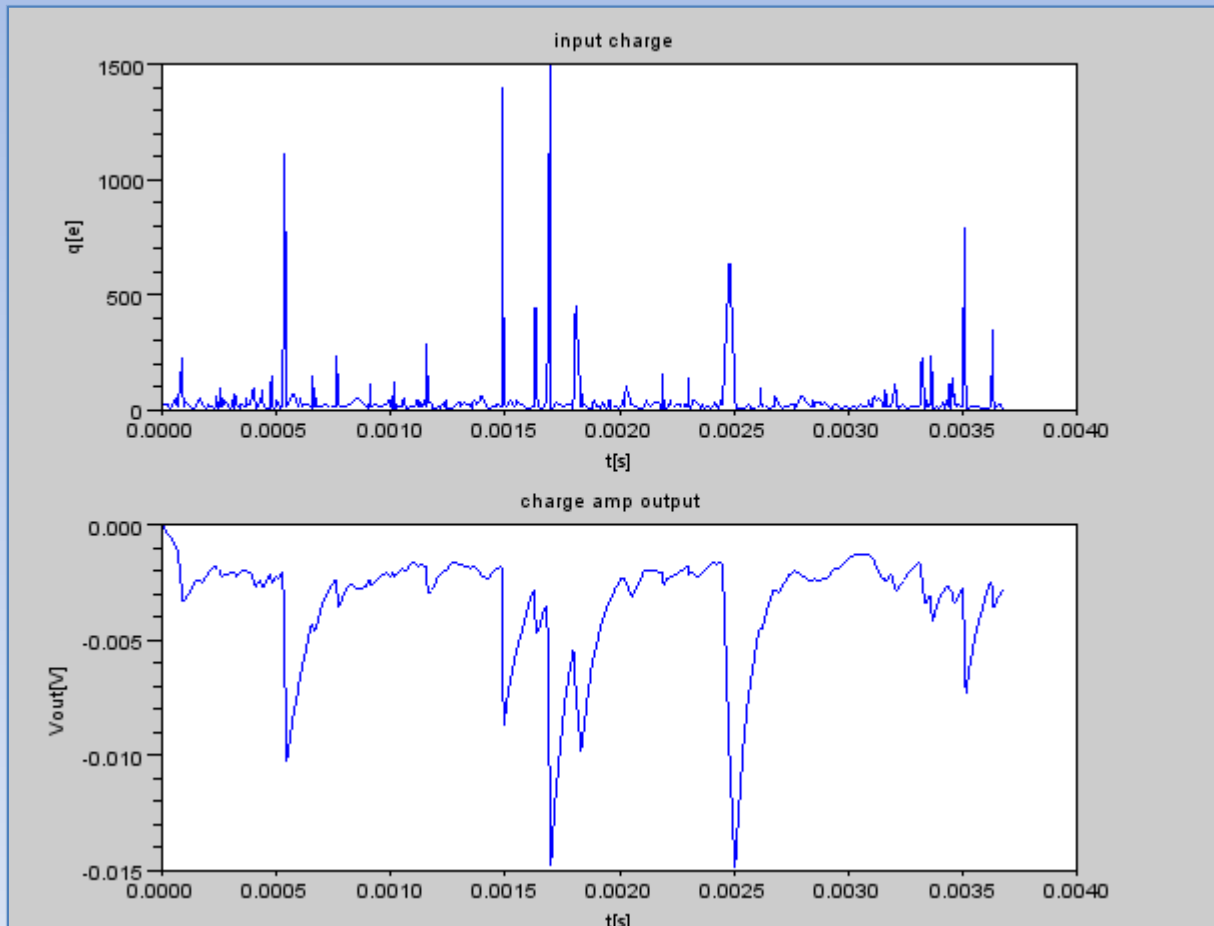
SIM: Diffusion-Drift Spectrum



Montecarlo sim of diffusion signal from sealed Fe55 source:

- Only 5.9keV photons propagated
- Accounts for
 - Source geometry
 - Pixel geometry
- Silicon deposition statistics
- Limited accuracy on recombination simulation
 - Negligible impact in our conditions
- Confirms (qualitatively) hybrid spectrum structure

SIM: Collected Charge and CSA Signal

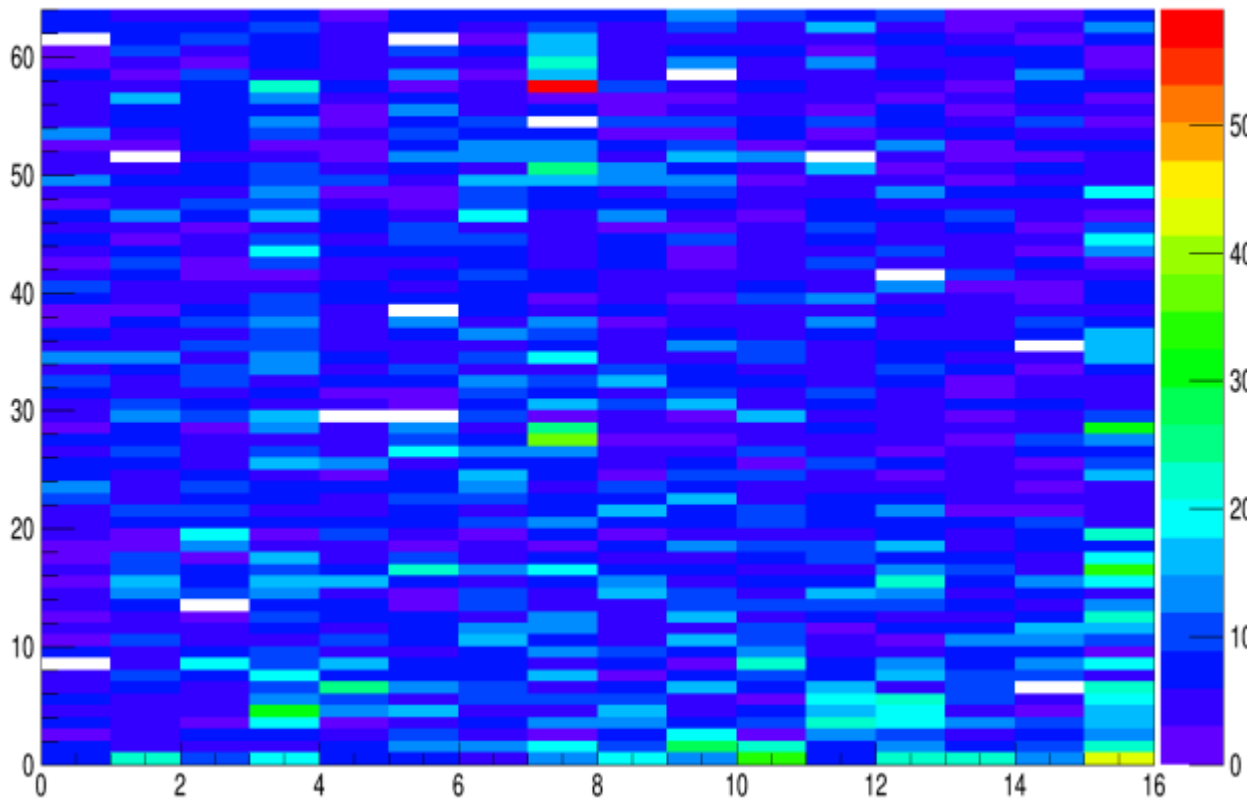


Montecarlo sim of diffusion signal from sealed Fe55 source:

- Continuous flow of small amounts of diffusion charge creates a drifting baseline output
- Occasional drift signal can easily pile-up
- Diffusion signal at high rates becomes 'noise' for drift signal
- Shaping useful to minimize pileup and restore baseline

Experimental: recent MIPs irradiation results

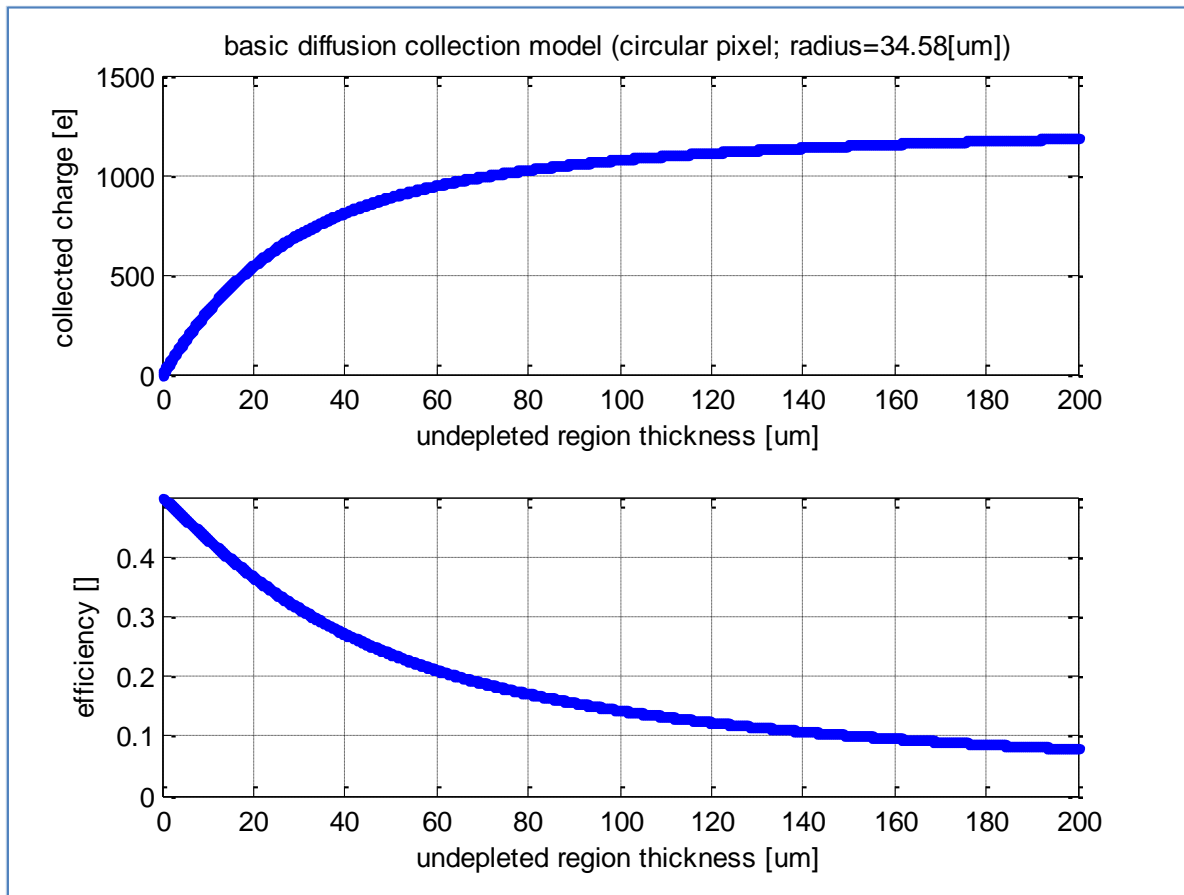
OCC



T3MAPS_P1 occupancy map w/i a 10Gev electron beam at SLAC:

- Threshold set to minimum value before firing on noise.
 - Adjustment done pixel by pixel...
- Comparison with IBL tracker indicates 50% hit efficiency
- Estimate threshold about 1700e⁻ (slide 8)
 - suggests that MIP signal median was also about 1700e⁻

Preliminary: Analytical Models for Collection-by-Diffusion



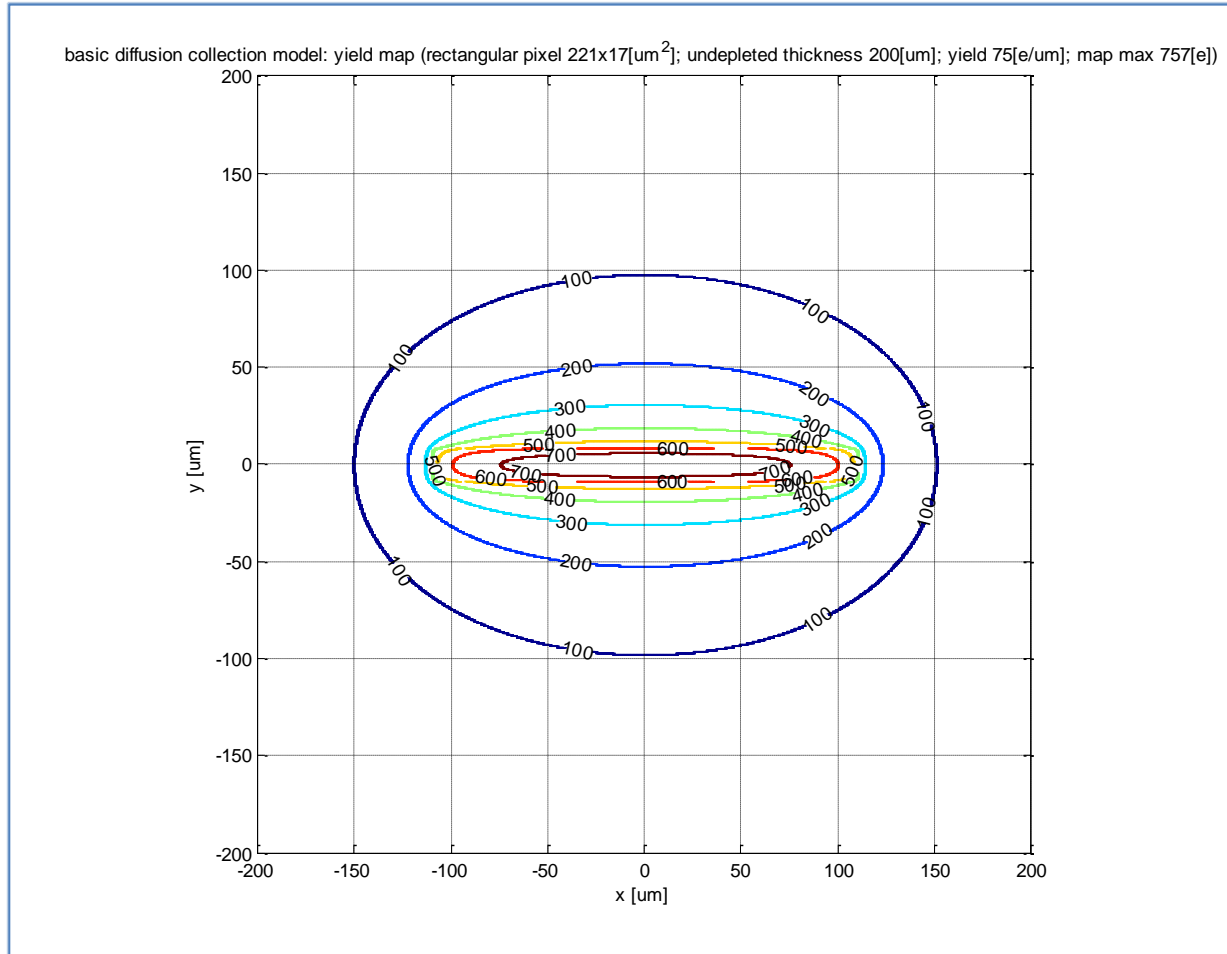
Analytical model of diffusion signal from MIP beam:

- Round pixel
- Orthogonal track
- Pixel center
- 221x17um² area-equivalent

Behavior vs deposition depth:

- Efficiency (wrt drift) quickly drops from 0.5 to 0 as $1/z^2$
- Collected charge saturates to a value lin dep on pixel size

Preliminary: Analytical Models for Collection-by-Diffusion



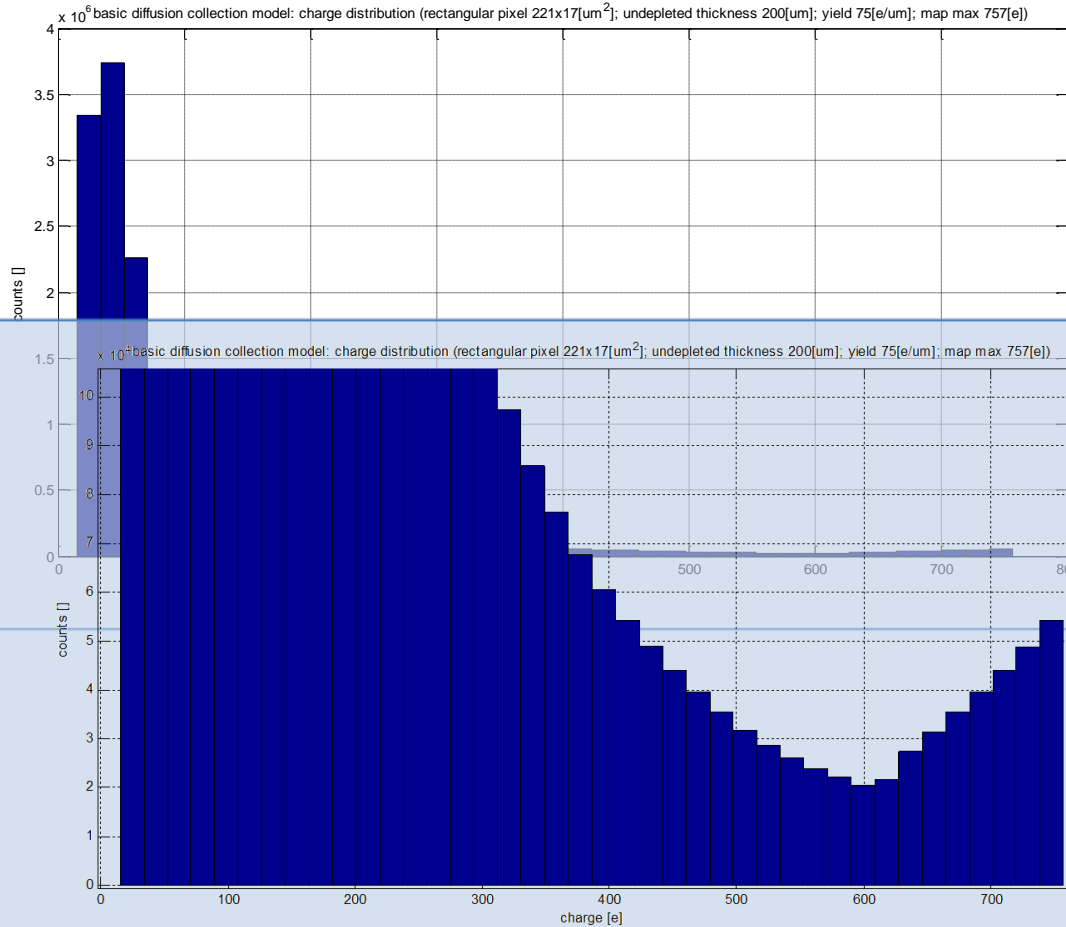
Analytical model of diffusion signal [e] from MIP beam:

- Rectangular pixel
- Orthogonal tracks
- $221 \times 17 \mu\text{m}^2$

Behavior vs track transversal distance:

- Charge-sharing can be significant
- Threshold can help limiting PSF
- Will be problematic at high rates

Preliminary: Analytical Models for Collection-by-Diffusion



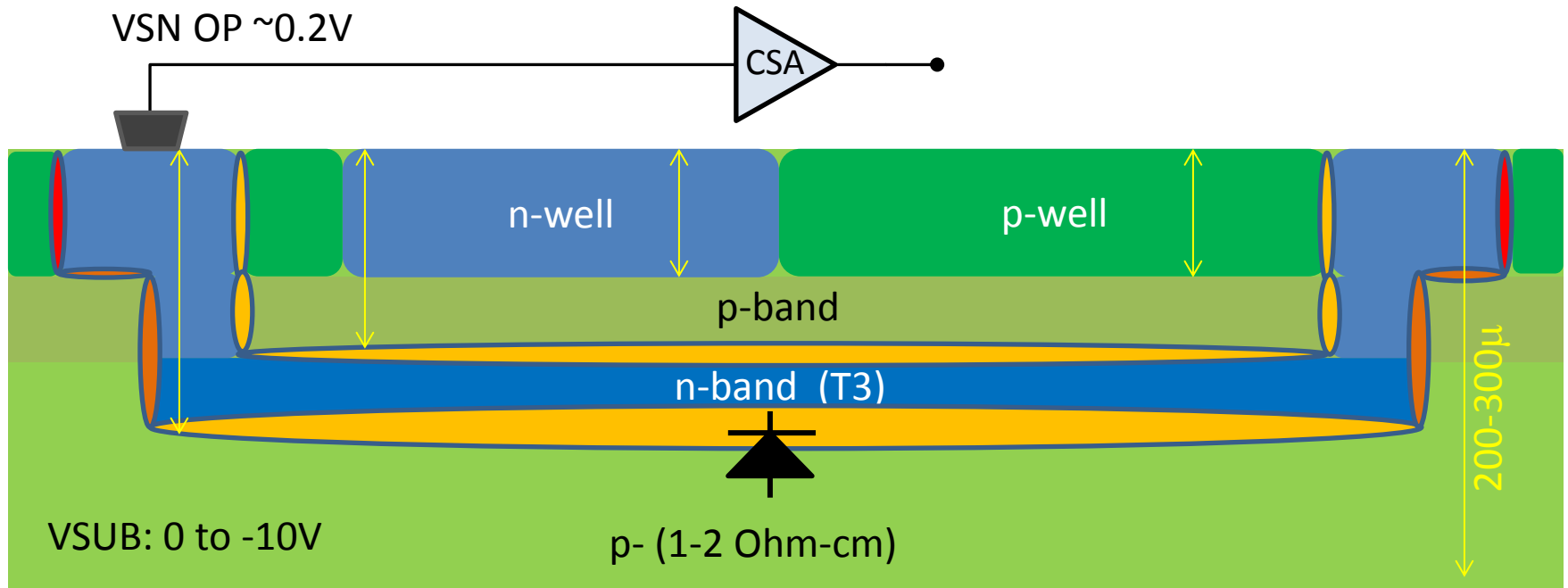
Analytical model of diffusion signal [e] from MIP beam:

- Rectangular pixel
- Orthogonal tracks
- 221x17um²

Collected charge distribution:

- Threshold is fundamental in limiting PSF
- high rates can be a significant problem...

Sensor limitations

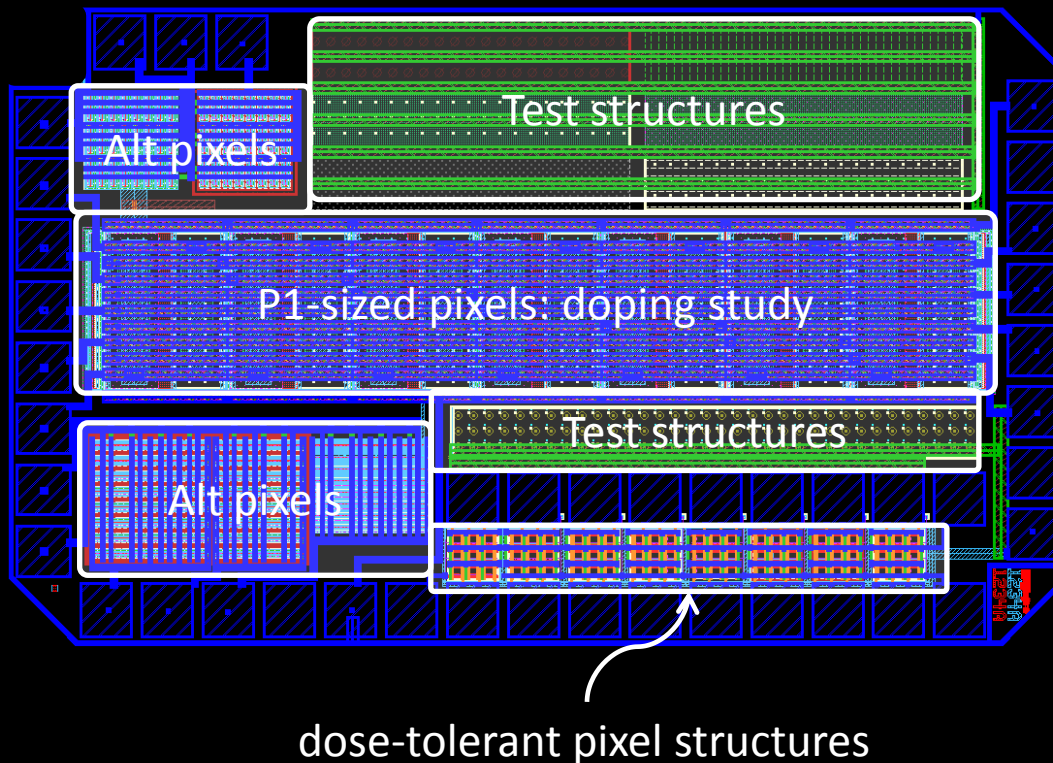


- S/N benefit from higher drift signal component
 - Increase depletion width
 - Increase BV (HR wafer were not available)
- Reasonable to assume surface twin-well junction determines BV
 - Limited silicon simulation data available...
- Intrinsic cap limitations from inner junction
 - CSA is DC-coupled...

First prototype results

- **Sensor**
 - Detection efficiency is limited by depletion layer thickness
 - Depletion width limited by substrate doping AND breakdown voltage
 - Foundry was not open to high-resistivity runs
 - Try custom devices options to increase breakdown voltage (assuming doping and not geometry is limiting factor)
 - Lost silicon simulation capability...
- **Electronics**
 - Operated as expected from simulation
 - Digital crosstalk into sensing node is negligible
- **Open Questions**
 - Avalanche effects
 - Rad tolerance
 - Possible BV optimization w/i process options
 - BV mechanism

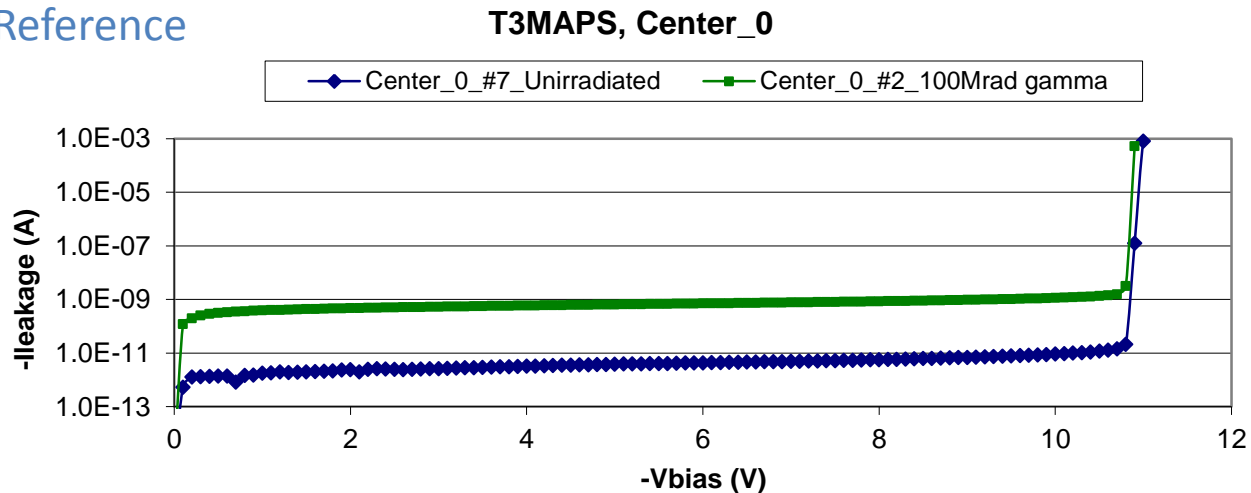
T3MAPS_P2: Layout



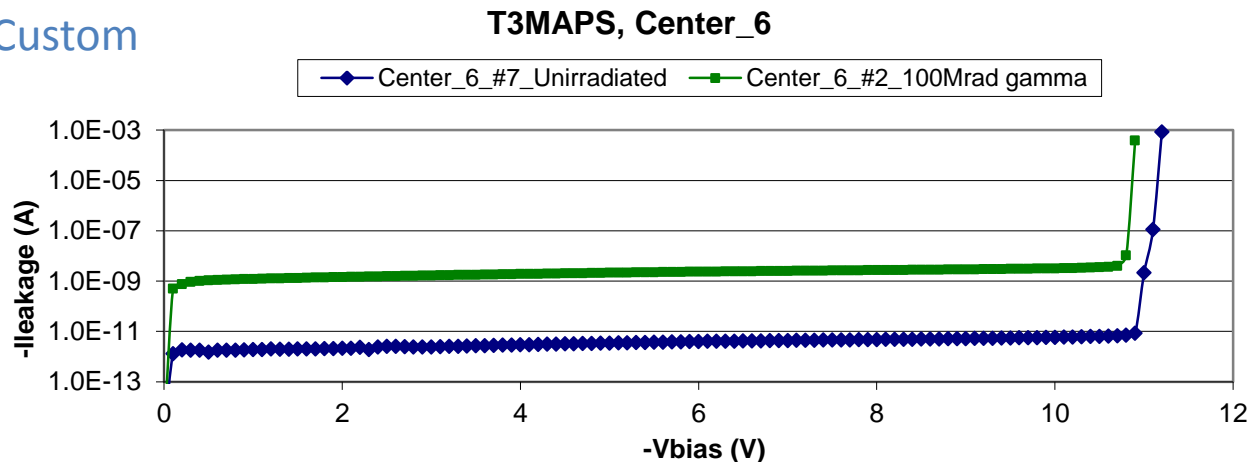
- Pixel optimization and process study
- Test sensor:
 - Breakdown optimization
 - Radiation tolerance
- Test Process:
 - Junction and implant measurements

Experimental: rad effects on I-V curves

Reference



Custom



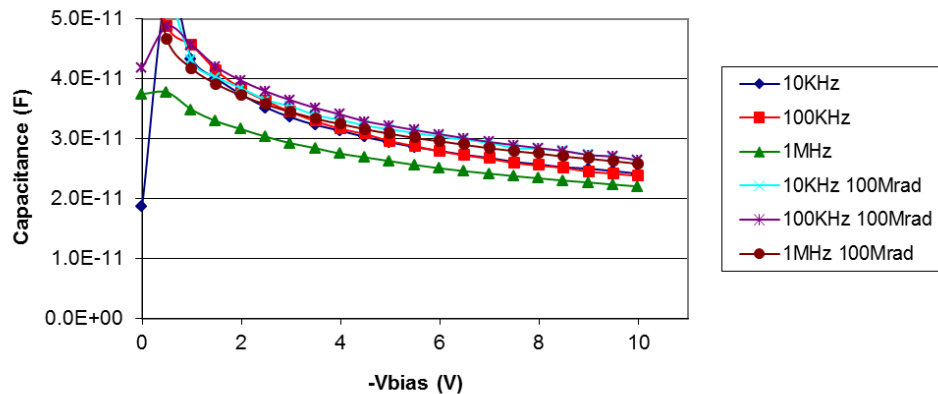
100Mrad gamma:

- Std junction
 - BV seems unaffected by irradiation
 - Leakage current increases by 2-3 orders of magnitude
- Custom junctions
 - BV effect are visible but minor
 - Similar levels of leakage increase
 - Not what we hoped for...

Experimental: rad effects on C-V curves

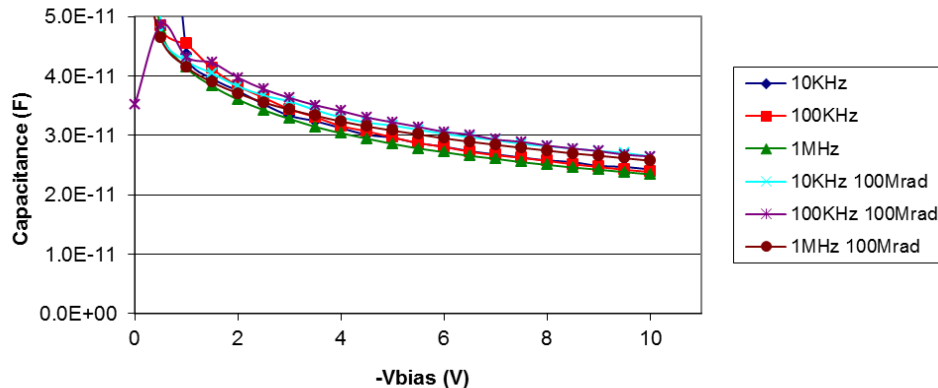
Reference

CV T3 #1 Cent_0



Custom

CV T3 #1 Cent_6

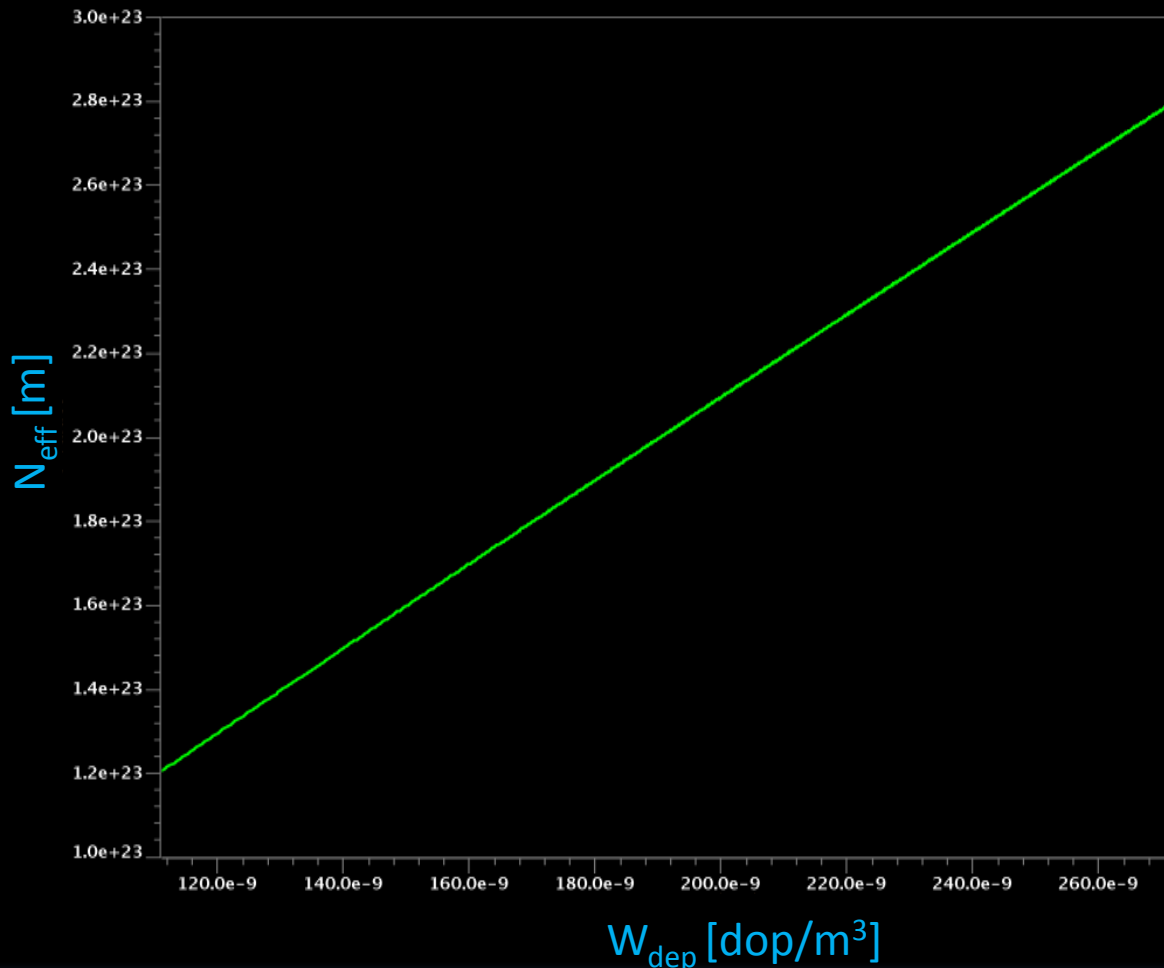


100Mrad gamma:

- Std junction
 - Irradiation causes a small increase in capacitance
 - Electrode resistance artifact in high freq measurements
- Custom junctions
 - No significant difference in sense node cap
 - Inner depletion dominates... still we were expecting some perimeter effects..

SIM: process info from models

Database : diodenwx_Sim November 6, 2013 / 8:01:30 AM dgnani / westmere3.lbl.gov



N_{eff} vs W_{dep} curve:

- Limited accuracy due to approximations
- Indicates orders of magnitude

Second prototype results

- Breakdown voltage
 - None of the implant-based solutions in the pixels tested so far was able to achieve significant BV increase
 - Possible explanations:
 - Junction geometry determines BV rather than doping
 - Undocumented foundry layer ops suppressed layers in custom structures
 - Additional structures present in the prototype were not tested
- Radiation Tolerance
 - Regular sense-node junction leakage is limited to 2-3 orders of magnitude at 100Mrad
 - Additional
- Process
 - Additional results could come from the analysis of C-V curve for approximate W_{dep} extraction
 - Additional test structures not analyzed
- Open Questions
 - Avalanche effects
 - BV mechanism
 - Performance of more complex structures

Conclusions

Main results

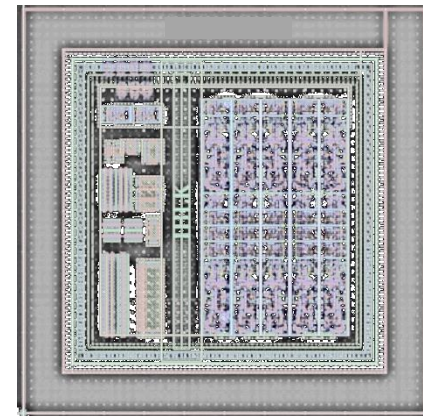
- Sensor and in-pixel electronics work but...
 - efficiency is limited
 - sense node cap too high
 - need higher ρ substrate

Open questions

- Unclear what prevented increase in BV
 - Suppression by logic op?
 - Junction curvature?
- Avalanche effects?

Future Plans

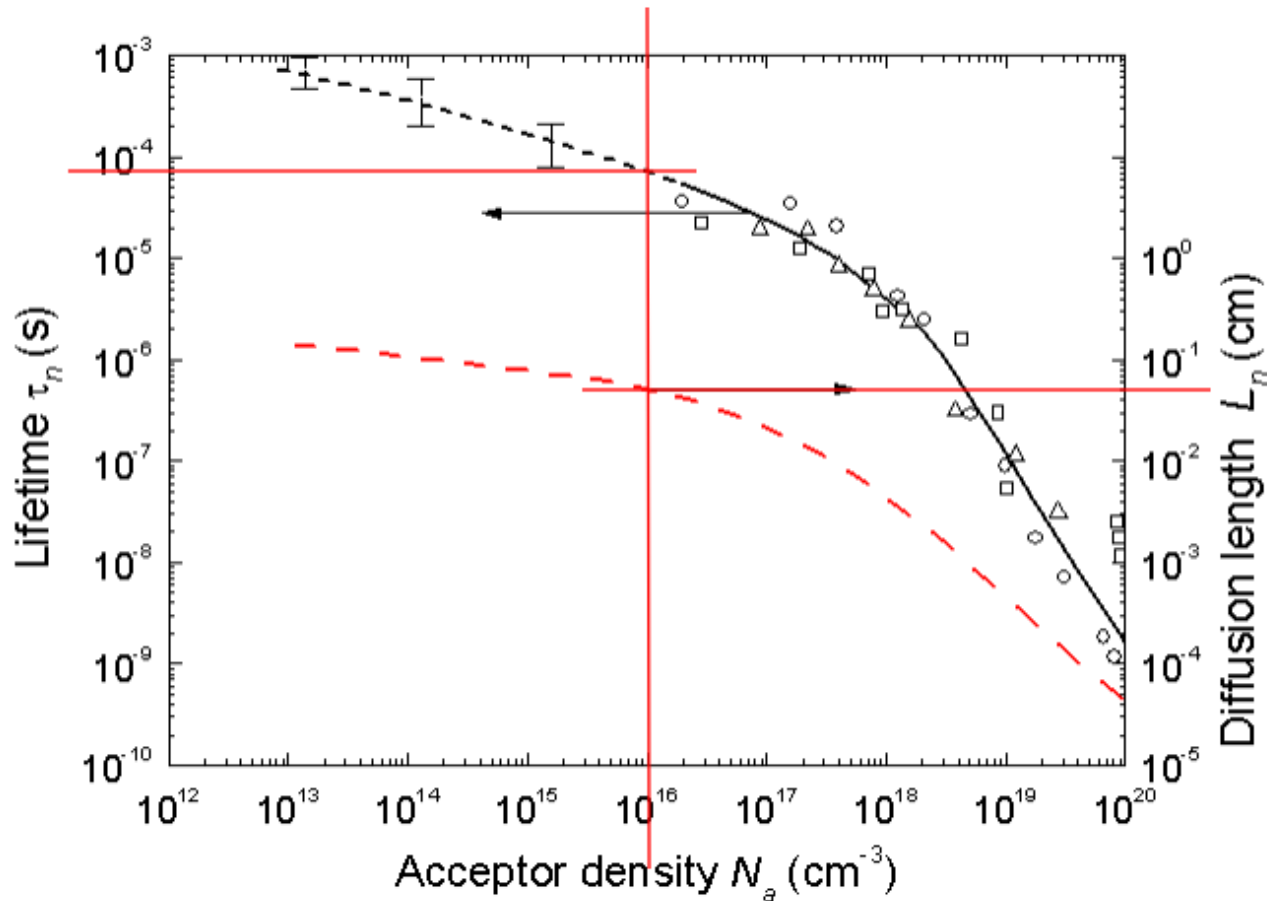
- New run using 50um square pixels
- Hope to use high resistivity substrate



Non-essential slides: details, very preliminary results, ...

ADDITIONAL SLIDES

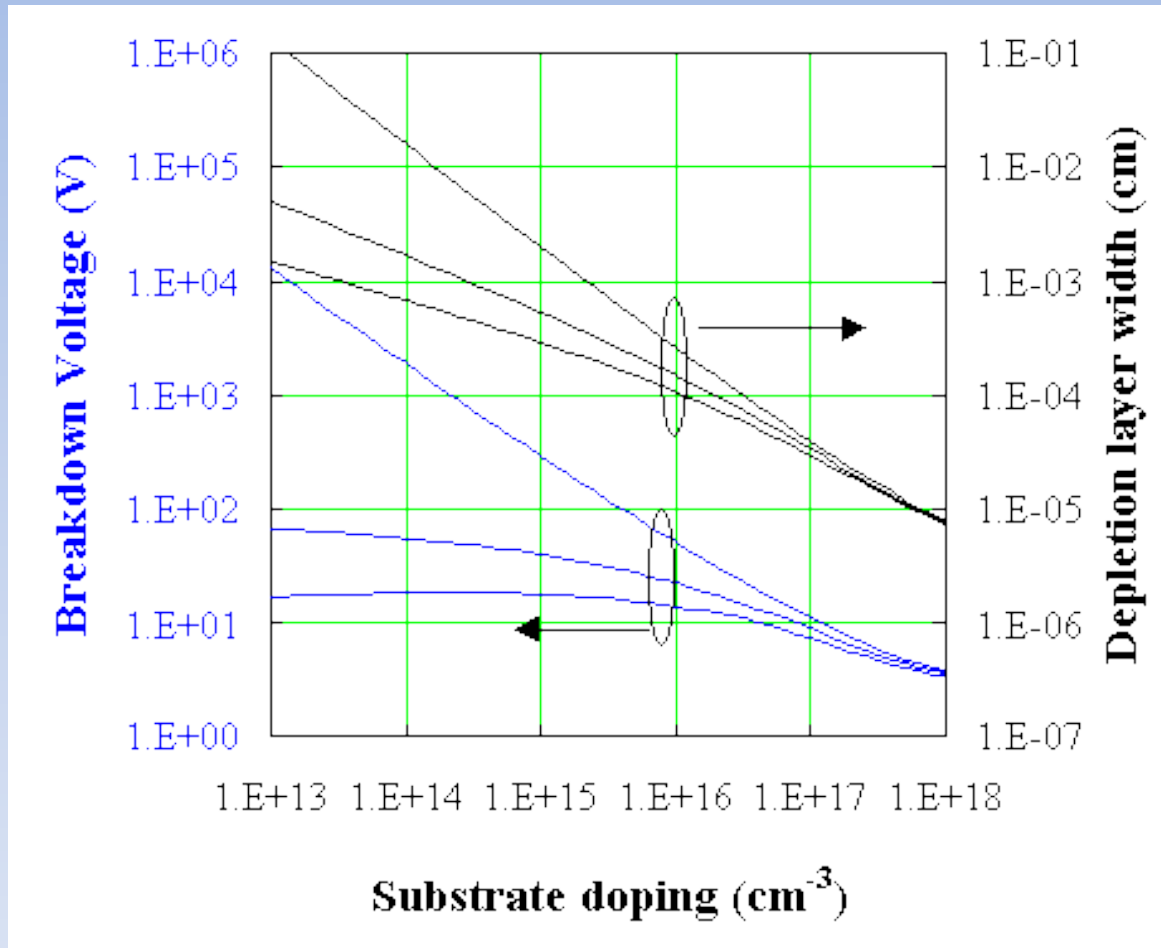
Phys: Diffusion in Si



Diffusion length and minority carrier recombination time in p-doped Si:

- $L_d \sim 500 \mu\text{m}$
- $\tau_e \sim 70 \mu\text{s}$

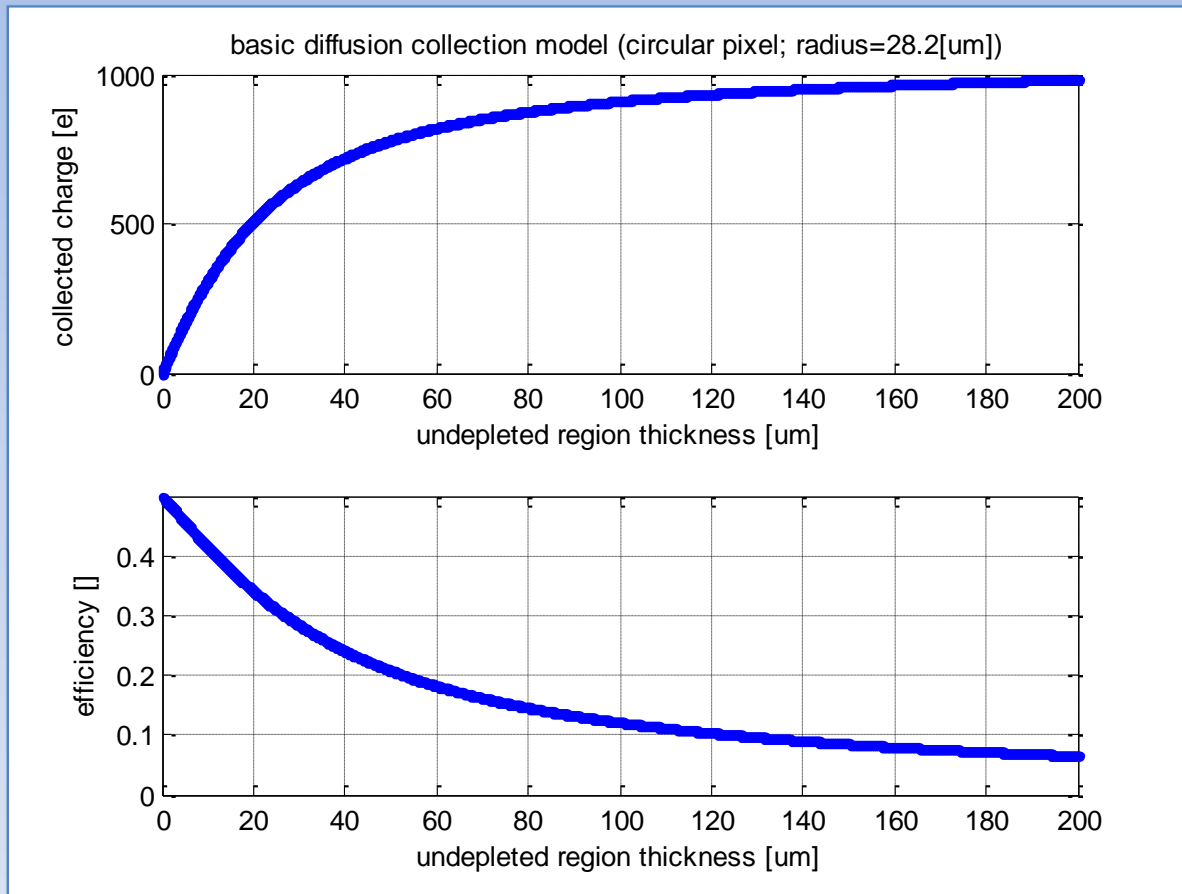
Phys: Abrupt junction curvature



Effect of flat, cylindrical and spherical curvature on BV and W_{dep} in an abrupt junction:

- Spherical junction
 - BV saturates below 10^{16}at/cm^3 doping level
 - Depletion width scaling goes from (almost) linear to increasingly sublinear

Preliminary: Analytical Models for Collection-by-Diffusion



Analytical model of diffusion signal from MIP beam:

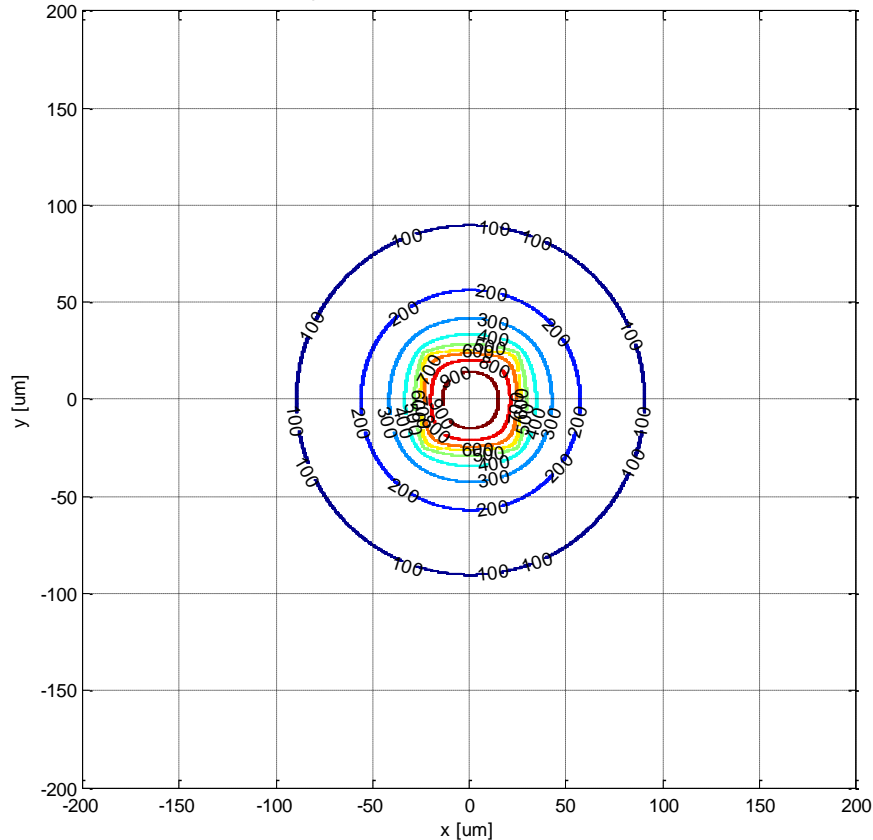
- Round pixel
- Orthogonal track
- Pixel center
- 50x50um² equivalent

Behavior vs deposition depth:

- Efficiency (wrt drift) quickly drops from 0.5 to 0 as $1/z^2$
- Collected charge saturates to a value lin dep on pixel size

Preliminary: Analytical Models for Collection-by-Diffusion

basic diffusion collection model: yield map (rectangular pixel $50 \times 50 [\mu\text{m}^2]$; undepleted thickness $200 [\mu\text{m}]$; yield $75 [e/\mu\text{m}]$; map max $978 [e]$)



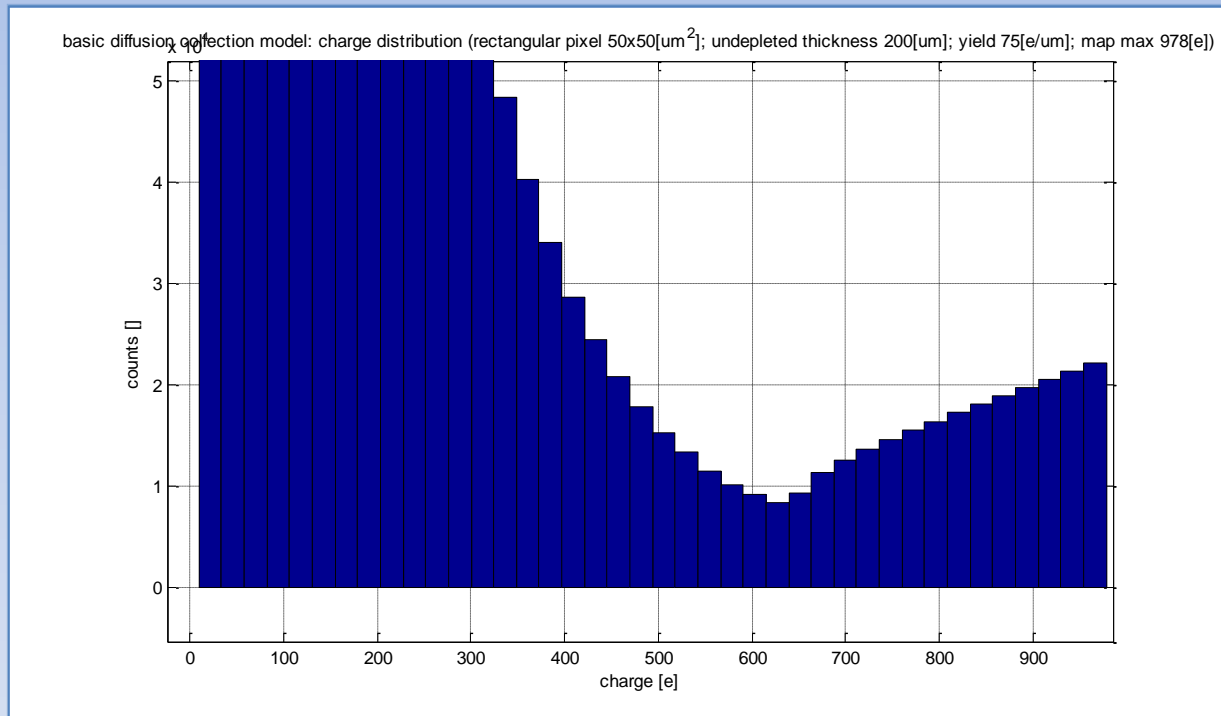
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Behavior vs track transversal distance:

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- Threshold can help limiting PSF
- Will be problematic at high rates

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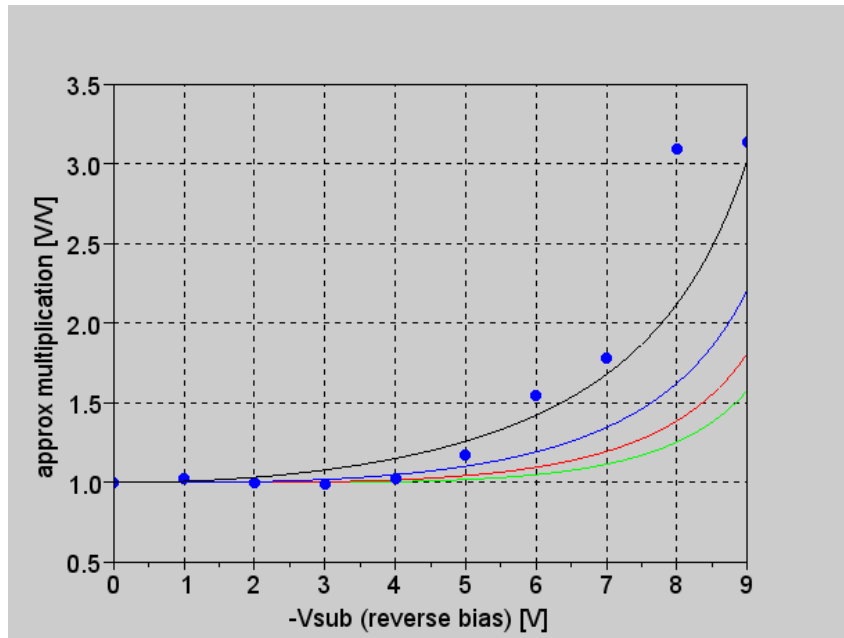
Analytical model of diffusion signal [e] from MIP beam:

- Rect pixel
- Orthogonal tracks
- $50 \times 50 \mu\text{m}^2$

Collected charge distribution:

- Threshold is fundamental in limiting PSF
- high rates can be a significant problem...

Experimental: High energy Tail



Sealed source hit test:

- 'large' hits above max expected energy
 - pile-up
 - OR
 - avalanche effects
- Require better statistics (high threshold spectrum)
 - ...